

- 15 -

**METHOD AND SYSTEM FOR DETERMINING A PERFORMANCE OF PLASMA
ETCH EQUIPMENT**

5

Abstract of the Disclosure

10 A method of determining a performance of plasma etch
equipment is provided. The method comprises extracting
data that depend on the performance of plasma etch equip-
ment, during etching of the wafer, for example by calcu-
lating an etch rate and by calculating a non-uniformity
of a film being etched. After that, the extracted data
are compared to predetermined data, and on the basis of a
15 result of comparing the extracted data with predetermined
data the performance of the plasma etch equipment is de-
termined. Further, a system for determining a performance
of plasma etch equipment is provided.

20 (Figure 1)